

# AV710-NE

## AGX XAVIER RUGGED COMPUTER



- NVIDIA<sup>®</sup> Jetson AGX Xavier<sup>™</sup> with 512-Core Volt a GPU with 64 Tensor cores
- Multi Video Format Frame Grabber Support
- SDI/HD/3G-SDI Input by Mini PCIe or M.2
- PAL/NTSC Input By Mini PCIe or M.2
- 1x CAN Bus, 1x RS485 , 2x USB, 2x LAN
- 1 x NVMe (PCle Gen4x 4) By Option
- MIL-461 18V~36V DC-DC
- MIL-810 Vibration & Shock Resistance
- Extended Temperature Support -40°C to +65°C

## **Features**

#### • Al Interface Solution, NVIDIA Jetson AGX Xavier Module

**AV710-X2-Xavier** is 7STARLAKE ruggedized AI Edge platform specifically designed for NVIDIA<sup>®</sup> JETSON AGX Xavier module. Utilizing 7STARLAKE' Open, Modular, Scalable Architecture. In addition to AGX Xavier module, AV710-X2-Xavier provides one M.2 NVMe slot for fast storage access. Combining stunning inference performance, powerful CPU and expansion capability, it is the perfect ruggedized platform for versatile edge AI applications.

**AV710-X2-Xavier** ruggedized AI inference platforms designed for advanced inference acceleration applications such as voice, video, image and recommendation services. It supports NVIDIA<sup>®</sup> Jetson AGX Xavier GPU, featuring 11 TFLOPS in FP16 and 22 TOPs in INT8 for real-time inference based on trained neural network model.

GPU	512-core Volta GPU with Tensor Cores
CPU	8-core ARM v8.2 64-bit CPU, 8MB L2 + 4MB L3
Memory	32GB 256-Bit LPDDR4x   137GB/s
Storage	32GB eMMC 5.1
DL Accelerator	(2x) NVDLA Engines
Vision Accelerator	7-way VLIW Vision Processor
Encoder/Decoder	(2x) 4Kp60   HEVC/(2x) 4Kp60   12-Bit Support
Size	105 mm x 105 mm x 65 mm
Deployment	Module (Jetson AGX Xavier)

#### **The Tech Specs**

**JETSON AGX XAVIER** 







**AV710-X2-Xavier** offers an extension to Frame grabbers which is extremely vital in applications related to agile reconnaissance, e.g., target acquisition, smart surveillance, and security. For instance, when a potential breach of abnormal signal is detected, a frame grabber captures an image or a sequence of images in digital form, and then transmits the data to user and command control center. By adding a slim frame grabber card, **AV710-X2-Xavier** can collect useful images and help our clients to react promptly on the ever-changing world.

# **Specifications**

#### **System**

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Processor	8-core ARM v8.2 64-bit CPU, 8MB L2 + 4MB L3.	
Memory type	32GB 256-Bit LPDDR4x   137GB/s	
Chipset	AGX XAVIER	
GPU		
NVIDIA	JETSON AGX XAVIER	
CUDA Cores Memory	512-core Volta GPU with Tensor Cores	
	32GB 256-Bit LPDDR4x   137GB/s	
Storage	32GB Emmc x 1	
Graphics Output		
1x DVI	DVI	
Resolution	Up to 1920x1200@60Hz 32bpp	
Storage		
HDD/SSD	1x M.2 2280 M key NVMe socket (PCIe Gen3 x4) for NVMe	
	SSD installation 1 x 2.5" SSD	
I/0		
Power Button	Water Resistive Power Button with LED Backlight	
Ethernet (X1, X2)	2 x LAN, total 4 x LAN	

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USB (X3)	2 x USB3.0		
DVI (X4)	1 x DVI		
COM (X5)	1 x RS485		
Audio (X6)	1 x 3.5mm Audio Jacks ( 1 x MIC, 1 x Line-Out )		
CAN (X7)	1 x CAN		
DC-IN (X8)	1 x DVI		
BNC (X9)	1x HD-SDI		
Power Requirement			
Power Input	DC-DC 18 to 36V (300W max) Mil-STD 461		
Applications, Operating Syst	iem		
Applications	Commercial and Military Platforms Requiring Compliance to		
	MIL-STD-810		
	Process Control, where Harsh Temperature, Shock, Vibration,		
	Altitude,		
	Dust and EMI Conditions.		
Operating System	Linux Ubuntu18.04		
Physical			
Dimension (W x D x H)	230 x 83 x 280 (mm)		
Weight	ТВС		
Chassis	Aluminum Alloy, Corrosion Resistant		
Finish	Anodic aluminum oxide		
Cooling	Natural Passive Convection/Conduction. No Moving Parts		
Ingress Protection	IP65		
Environmental			

Environmental



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### MIL-STD-810G Test

Low	Method 502.4	-20°C, 4 hours, change rate:
Temperature	Procedure 2	≦20°C.
High Temperature	Method 501.4	+55°C, 4 hours, change rate:
	Procedure 2	≦20°C.
Humidity	Method 507.4	85%-95%RHwithout condensation, 24 hours/ cycle, conduct 10 cycle.
Vibration	Method 514.5	5-500Hz, Vertical 2.20Grms, 40mins x 3axis.
Shock	Method 516.5	20 Grms, 11ms, 3 axes.

## Non-Operating Tests

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Low Storage	Temperature	Method 502.4	-33°C, 4 hours, change rate: $\leq$ 20°C.
High Temperatu	Temperature	Method 501.4	+71°C, 4 hours, change rate: $\leq$ 20°C.
Storage		Procedure 1	$\pm$ / 1 C, $\pm$ 110013, change rate. $\geq$ 20 C.
Vibration		Method 514.5	5-500Hz, Vertical 2.20Grms, 40mins x 3axis.
Shock		Method 516.5	20 Grms, 11ms, 3 axes.
EMC complianceMIL-STD-461E : CE102 basic curve, 10kHz - 30 MHz RE102-4, (1.5 MHz) -30 MHz - 5 GHz RS103, 1.5 MHz - 3 GHz, 50 V/m equal for all freque RS103, 3 GHz - 5 GHz, 50 V/m equal for all frequence EN 61000-4-2: Air discharge: 8 kV, Contact discharge EN 61000-4-4: Signal and DC-Net: 1 kV 		0 MHz - 5 GHz Hz, 50 V/m equal for all frequencies , 50 V/m equal for all frequencies charge: 8 kV, Contact discharge: 6kV and DC-Net: 1 kV 5 vs. ground potential 1kV, Signal und 51000-4-2: Air discharge: 8 kV, Contact I and DC-Net: 1 kV EN 61000-4-5: Leads 1kV, Signal und DC-Net: 0.5 kV	

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	EN 61000-4-4: Signal and DC-Net: 1 kV	
	EN 61000-4-5: Leads vs. ground potential 1kV, Signal und	
	DC-Net: 0.5 kV EN 55022, class A	
	EN 61000-4-3: 10V/m	
Operating	-40 to 65°C ( Ambient with air flow)	
Temperature		
Storage Temperature	-40 to 85°C	

**Appearance & Dimension** 



